

XTPL®



## XTPL NEWSLETTER

JULY 2022



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## Ladies and Gentlemen,



The summer season has begun, which means that another quarter of 2022 is behind us. During this period, we were strongly focused on working directly with our clients. Although there were slightly fewer current reports at that time than at the very beginning of the year, we were very busy implementing evaluation activities as part of ongoing projects and cooperations with industrial clients. In this regard, the second phase of work on the product dedicated to Nano Dimension is coming to a close. In the second quarter, we also signed an important, first private label contract for the distribution of proprietary XTPL paste by the US company nScript.

Another highlight of the last quarter was certainly the scientific publication showcasing our technology in the prestigious international journal Nature Scientific Reports. Such publications, with prior verification of the content and underlying technology by reviewers, play an important role in promoting innovative solutions on a global scale.

In April and May, we also published financial results for 2021 and Q1 2022, respectively which provide clear confirmation of the announced transition of XTPL from an R&D company into an entity successfully commercializing its products and technologies.

Following this brief summary, we encourage you to read about other events that took place in recent months. If you have any questions, please do not hesitate to reach out to our investor relations team, which is available for you at [investors@xtpl.com](mailto:investors@xtpl.com).

Kind regards,  
Management Board of XTPL S.A.



# BUSINESS & COMMERCIALIZATION



At the beginning of June, we boasted a publication of a scientific article in Nature Scientific Reports, a journal that enjoys a reputation in the international scientific and industrial community.

#### XTPL TECHNOLOGY SHOWCASED IN THE PRESTIGIOUS INTERNATIONAL SCIENTIFIC JOURNAL NATURE SCIENTIFIC REPORTS

XTPL S.A., a global supplier of breakthrough nanoprinting solutions for the global market of modern electronics, has presented the operating mechanism and the possible applications of its proprietary ultra-precise deposition (UPD) technology in the renowned international scientific journal Nature Scientific Reports. Prepared by the Company's team, the article was released as an open-access publication, which will ensure an even wider promotion of the XTPL technology around the world.

> [READ MORE](#)



Another important event in Q2 2022 was also the achievement of a milestone in the cooperation with the Israeli company Nano Dimension. XTPL completed the first stage of development as part of the technological phase of the activities specified in the agreement relating to development of a new generation conductive nanoink for industrial applications in the Nano Dimension's products designed for the production of PCBs. Completion of the first stage of the technological phase and the Client's approval of the work triggers the payment of the first tranche to XTPL.

↓ [ESPI CURRENT REPORT NO. 10/2022 OF 11 APRIL 2022](#)



April 2022 was a very fruitful time. In the first half of the month, XTPL concluded an agreement with the US company nScript for the distribution of our proprietary conductive paste CL85.

#### XTPL NANOINKS TO BE OFFERED BY THE US COMPANY NSCRYPT

XTPL S.A. is strengthening its cooperation with nScript Inc. – a US manufacturer of microdispensing, 3D manufacturing, and biomanufacturing equipment for industrial applications – by signing a license agreement with the company. XTPL's Ag Nanopaste CL85 will be added to nScript's product offer and will be marketed to nScript's production system users from medical device, defense and space sectors.

> [READ MORE](#)

[↓](#) [ESPI CURRENT REPORT NO. 9/2022 OF 5 APRIL 2022](#)



# TECHNOLOGY & DEVELOPMENT





Technology and new product development is one of the pillars of our business. In this process, we carefully observe the market and sectors in which XTPL solutions could be used. Our goal is full commercialization of our three business lines and implementation of the UPD technology for industrial use. For this reason, we find it important to appear at industry events: conferences, fairs and symposia. This not only helps promote XTPL and build awareness of our solutions, but above all allows us to establish a network of contacts and business relations.

Last quarter, our team and representatives were present at:



26-28/04/2022  
Smart Systems Integration  
Conference  
FRANCE



8-13/05/2022  
Display Week  
USA



11-12/05/2022  
Impact'22  
POLAND



31/05-3/06/2022  
The Electronic Components and  
Technology Conference (ECTC)  
USA



30/05-2/06/2022  
Euspen  
SWITZERLAND



9/06/2022  
Łukasiewicza Innovatorium  
POLAND



22-23/06/2022  
Chemnitzer Seminar 2022  
GERMANY



24/06/2022  
TechBlick  
VIRTUAL



In June this year, we started intensive work on the application of photonic sintering techniques for our Ag structures. Photonic sintering with the use of flash lamp helps dramatically accelerate the entire sintering process, which is reduced to less than a millisecond, regardless of the area subjected to it. As a result of appropriate optimization and selection of sintering parameters, this technique ensures good conductivity of structures even on substrates that cannot be subjected to temperatures above 100°C (flexible substrates, displays).

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Last quarter, we introduced the possibility of automated movement of the printing head for high-resolution automated printing on 3D surfaces such as lenses, high steps and elevations. Using the hardware extension that we have developed, our system is able to connect the features on both sides of the electrical circuit substrate, thus opening the way to applications in the area of advanced electronic micromassembly techniques.



In addition to the XTPL proprietary scripting language, which ensures full control over the production of structures by means of our system, we also develop a graphical interface that will make working with our device even simpler and more intuitive, reducing the time needed to design solutions.

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The XTPL technology is gradually being implemented by our clients into their microelectronic structure fabrication processes. Conventional techniques used in those processes tend to be unreliable and do not always afford appropriate precision – sometimes the produced structures are out of scale or slightly rotated. Such errors in assembling structures layer by layer may result in incorrect operation of the final system. That's why we have extended our software with the functionality of automatic adaptation of the print design using our technology to structures produced at earlier technological stages. By using the XTPL technology here, it's possible to build complex layered systems, even if the previous layers have slight geometric errors.



# INTELLECTUAL PROPERTY PROTECTION



On 11 May 2022, we received information about the approval of a patent for the Company by the United States Patent and Trademark Office for its method of forming lines of several hundred nanometers wide using the XTPL-developed silver nanoink, i.e. for the patent application “METHOD FOR REMOVING BOTTLENECKS”.

Notably, our solution facilitates the removal of possible local bottlenecks in the lines deposited during the printing process, thereby increasing the lines’ electrical conductivity and their current and mechanical strength.

The application procedure for this patent was initiated on 6 June 2018. This is also the date when patent protection started for the invention. At present, our portfolio includes 24 patent applications and a total of 2 patents granted.

> [READ MORE](#)



# INVESTOR RELATIONS



The end of June is usually the time of general meetings and formal summaries of the previous year. In the case of XTPL, two general meetings took place:

**21.06.2022**

Extraordinary General Meeting, which decided to change the Terms of Issue of Series A Bonds, including deferral of their redemption date to 30 January 2024.

[↓](#) ESPI CURRENT REPORT NO. 16/2022 OF 21 JUNE 2022

**30.06.2022**

The Annual General Meeting, which adopted the financial statements of XTPL for 2021 and granted discharge to the members of the Management Board and Supervisory Board for performance of their duties in 2021.

[↓](#) ESPI CURRENT REPORT NO. 19/2022 OF 30 JUNE 2022



In the second quarter of 2022, the Company and its Bondholders agreed on changes to the Terms of Issue of the Series A Bonds issued in 2020. Two of the three Bondholders decided to accept the changes to the Terms and deferral of the redemption date by 18 months, and an increase in the interest rate on the Bonds to 5% per year. The third of the Bondholders and the Company agreed to redeem the bonds at their original maturity date, i.e. 30 July 2022.

[↓](#) ESPI CURRENT REPORT NO. 12/2022 OF 25 MAY 2022

In April and May 2022, we published two periodic reports: the annual report for 2021 and the quarterly report for the first quarter of 2022.

2021 A BREAKTHROUGH YEAR FOR XTPL GROWTH

[>](#) READ MORE

[↓](#) 2021 ANNUAL REPORT

IN Q1 2022, XTPL CONCLUDES STRATEGIC AGREEMENTS WITH THE RESULTING REVENUES TO HELP THE COMPANY'S CONTINUED STRONG GROWTH

[>](#) READ MORE

[↓](#) REPORT FOR Q1 2022





## CONFERENCES FOR POLISH AND INTERNATIONAL INVESTORS

In the past period, XTPL was also very active and participated in many investor meetings. We self-arranged earnings calls that are already a permanent part of our financial communication. During those meetings, we present you the financial results achieved in a given period and the most important achievements. In addition, we also took part in popular, recurring investor conferences in Poland and abroad:



04/2022  
Institutional Investors  
Conference Zürs 2022  
AUSTRIA / VIRTUAL



04/2022  
#GPW Innovation Day  
VIRTUAL



05/2022  
Equity Forum German Spring  
Conference  
GERMANY



05/2022  
Virtual Technology & Innovation  
Conference 2022 (Erste)  
VIRTUAL



43.80 PLN

SHARES PRICE

2022-07-05

## RESULTS PRESENTATION

For Q1 2022

[↓](#) DOWNLOAD

DOWNLOAD

21 **SEP**  
WED

## PUBLICATION OF THE INTERIM REPORT

for the first half of 2022

22 **NOV**  
TUE

## PUBLICATION OF THE INTERIM REPORT

for the third quarter of 2022

INVESTOR'S CALENDAR

# STAY IN TOUCH

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FOR MORE INFORMATION GO TO  
OUR INVESTOR RELATIONS SITE

